SUSS

November 25/26, 2024

Investor Presentation

Deutsche Börse Equity Forum
Frankfurt

SUSS at a glance

- Hidden champion headquartered in Germany with 75 years track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry, benefiting from structural growth drivers such as Artificial Intelligence
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities

SUSS MicroTec is part of our digital life!

Management Board of SUSS MicroTec SE

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CFO
Dr. Cornelia Ballwiesser

- Finance & Controlling
- Legal & Compliance
- Internal Audit
- Investor Relations
- IT
- ESG

CEO
Burkhardt Frick

- Sales and Service
- Strategy
- HR
- Business Units:
  Advanced Backend Solutions,
  Photomask Solutions

COO
Dr. Thomas Rohe

- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Product Center
- Facility Management

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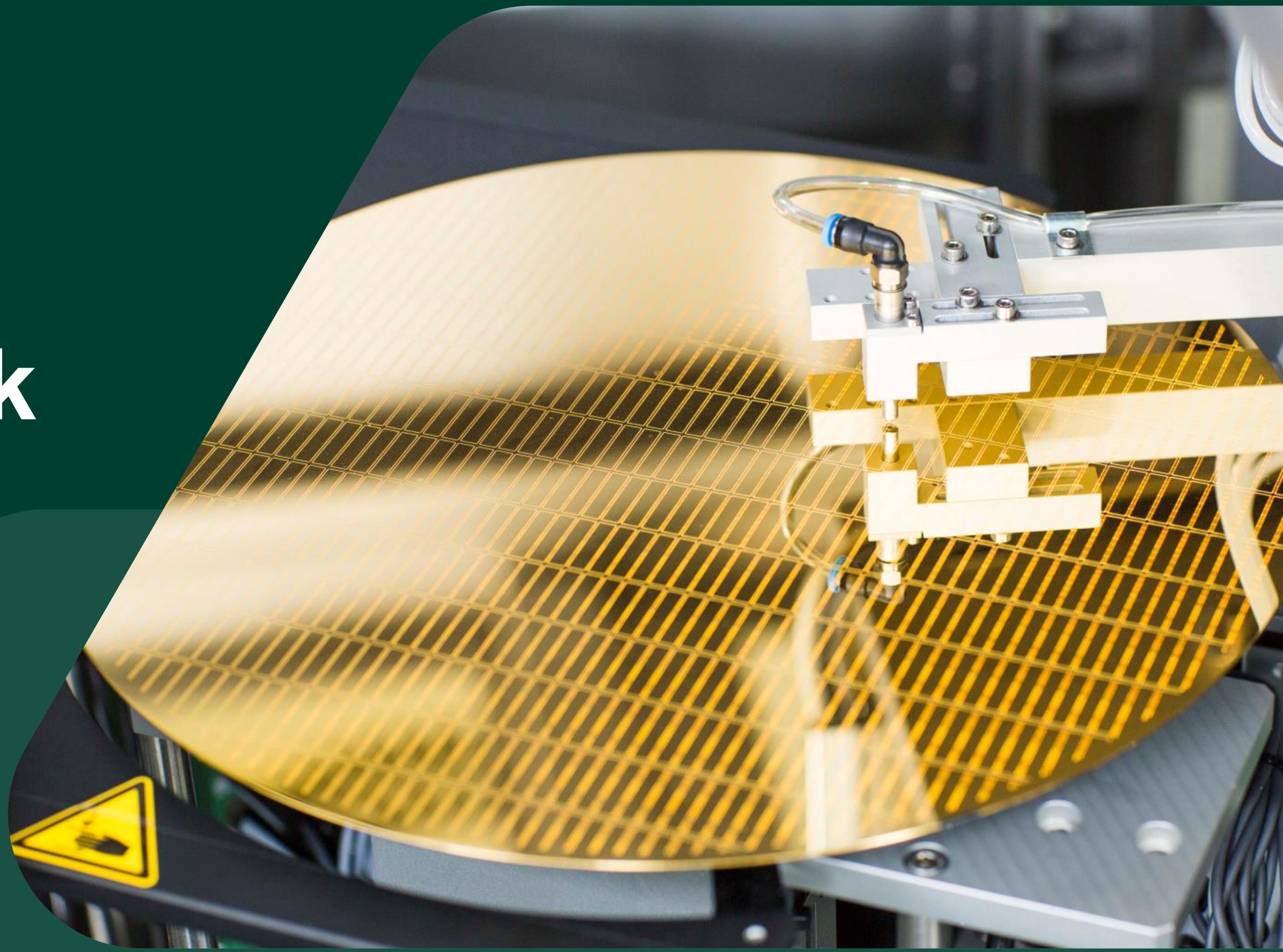
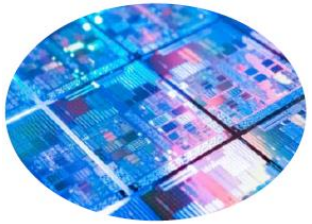
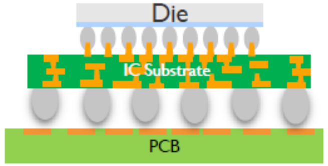
Leader in enabling innovative advanced backend & photomask solutions

Our vision



Our world are the semiconductor frontend and backend process steps





Wafer fabrication

Front-end-of-line Wafer process

- Deposition/coating
- Cleaning
- **Patterning/lithography**[1]
- Etching
- Implantation
- Annealing
- **Permanent bonding**
- **Temporary bonding**
- CMP polishing

From middle-of-line to back-end-of-line

Advanced packaging

- Deposition/coating
- Cleaning
- **Patterning/lithography**
- Etching
- Annealing
- CMP polishing
- **Permanent bonding**
- **Temporary bonding**
- **Wafer level packaging**
- Wafer dicing
- Panel-level packaging

Final packaging

- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

1 Only related to Photomask processing
Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

Our two segments, mainly serving the semiconductor industry

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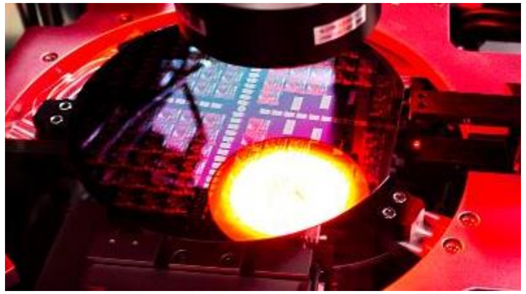
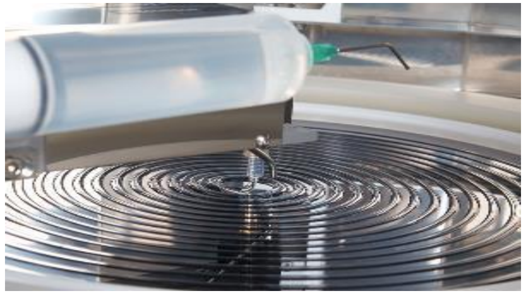
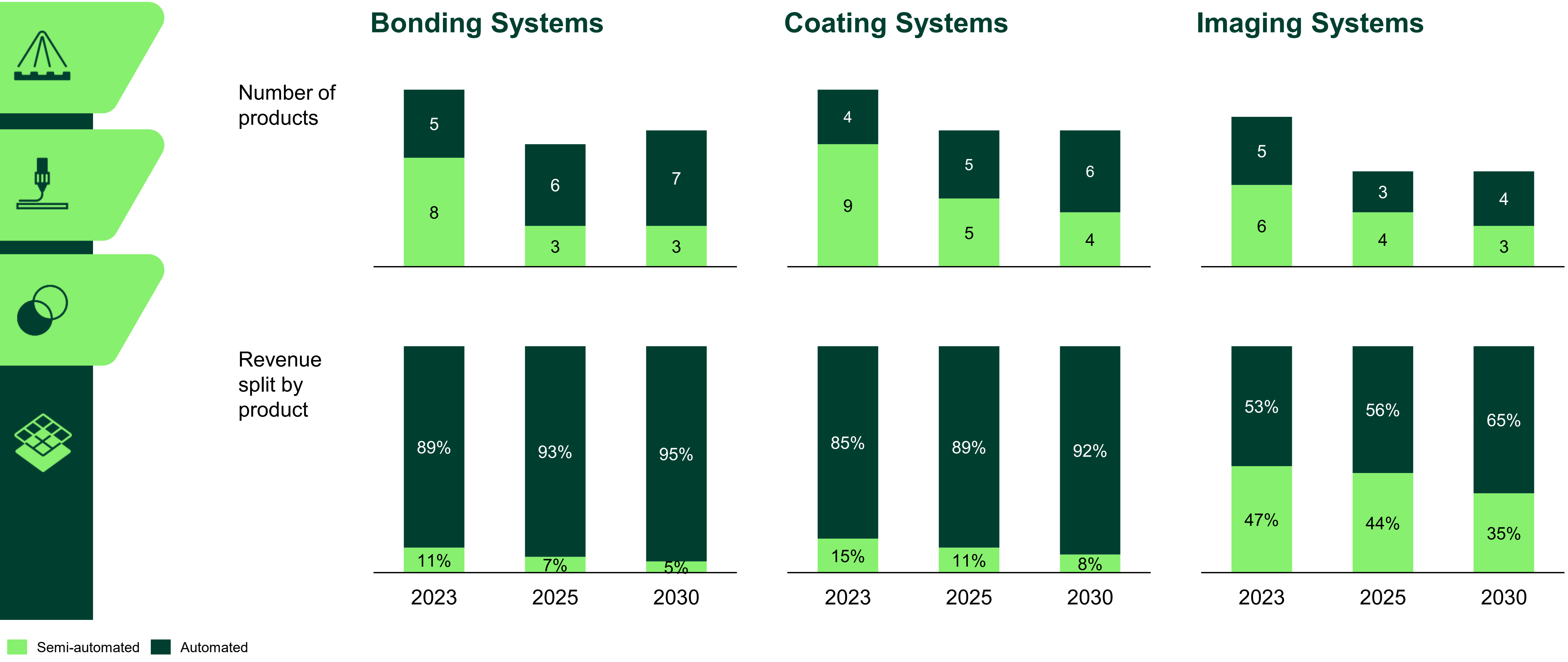
	Frontend	Advanced Backend		
Segments	Photomask Solutions	Advanced Backend Solutions		
				
Products	**Photomask Equipment**	**Imaging**	**Coating**	**Bonding**
	 MaskTrack X	Mask Aligner MA200/300   UV Projection Scanner DSC300	 ACS300	XBC300   XB8

Focus on high-volume manufacturing markets while semi-automated tools will be phased-out during next years in Advanced Backend Solutions business unit



Full range of bonding solutions by SUSS

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Temporary Bonding	Permanent Bonding	Hybrid Bonding	
Temporary Bonding XBS300 	Bonding (200 mm) XBS200 	W2W (up to 200 mm) XBS200 	W2W (up to 300 mm) XBS300 W2W 
De-bonding/Cleaning XBC300 Gen2 		D2W & W2W XBC300 Gen2 D2W/W2W 	D2W XBC300 Gen2 D2W 
Mech. De-bonding (semi-auto) DB12T 	High-force Bonding (semi-auto) SB8 Gen2/XB8 		

SUSS hybrid bonding solutions – understanding customer’s needs

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Wafer-to-wafer HB
XBS300 W2W

Product launch: 10/2022
Target customers: HVM

Die-to-wafer/wafer-to-wafer HB
XBC300 Gen2 D2W/W2W

Product launch: 05/2024
Target customers: Research institutes, R&D teams of HVM

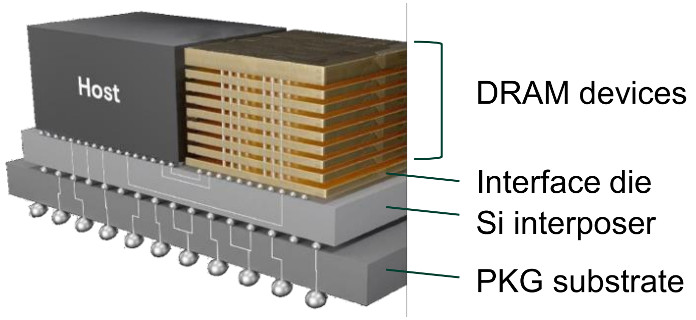
Die-to-wafer HB
XBC300 Gen2 D2W

Product launch: Q4/2024
Target customers: HVM

We optimize our product solutions to serve our customer’s device and manufacturing needs.

HBM roadmap enables SUSS to grow in existing and new markets

in € million	HBM3E	HBM4	HBM4E	HBM5
Expected SOP	2024	2025	2026 or 2027	2027 or 2028
# of DRAM layer acc. to JEDEC	8/12	12	16	16/20
Bonding type in DRAM stack	TCB	TCB	TCB or HB	HB
Thinning of DRAM devices	TBDB	TBDB	TBDB	TBDB



source: Micron, HBM3E

Relevance for SUSS:

1 TBDB remains a crucial process for thinning of DRAM devices used in HBM cube

Growth of existing SUSS TBDB business in line with general HBM market growth

2 Increase of layer number in HBM cube triggers more TBDB capacity for thinning of DRAM devices

Additional growth of SUSS TBDB business in line with higher layer in HBM cube

3 Hybrid bonding will gradually replace Thermal Compression bonding for stacking of DRAM devices

Expansion into this market offers new growth opportunities with SUSS HB solutions

TCB: Thermal compression bonding, HB: hybrid bonding, TBDB: Temporary bonding & de-bonding

We have built up additional temporary bonding capacity in Taiwan

- We added 50+ people in Hsinchu in order increase manufacturing capacity for temporary bonders
- First temporary bonder ‘made in Taiwan’ has been completed at the beginning of March 2024
- Full capacity available since Q3-2024
- Total manufacturing capacity for temporary bonding equipment (bonder, debonder and cleaner) in Sternenfels and Hsinchu allows us to generate yearly sales of ~ €150 million.

New, larger production site in Zhubei (Taiwan) prepares us for further targeted growth

1

Signing

of long-term lease agreement for new production site in Zhubei took place on October 23, 2024.

2

Completion

of shell is scheduled for the end of 2024. We will then carry out cleanroom and office installations with expected CAPEX of € 15-20 million.

3

Production start

at the new site is expected in the second half of 2025. The new factory offers the potential to double production capacity under clean room conditions to ~6,300 m².

Extraordinary, profitable growth continued in Q3 2024

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Financial Results

9M 2024[1]

276.2	295.3	39.6	16.1
in € million	**in € million**	**in %**	**in %**
Order intake 9M 2024	Sales 9M 2024	Gross profit margin 9M 2024	EBIT margin 9M 2024
-1.8% YoY	**+46.0% YoY**	**+6.1pp YoY**	**+9.8pp YoY**

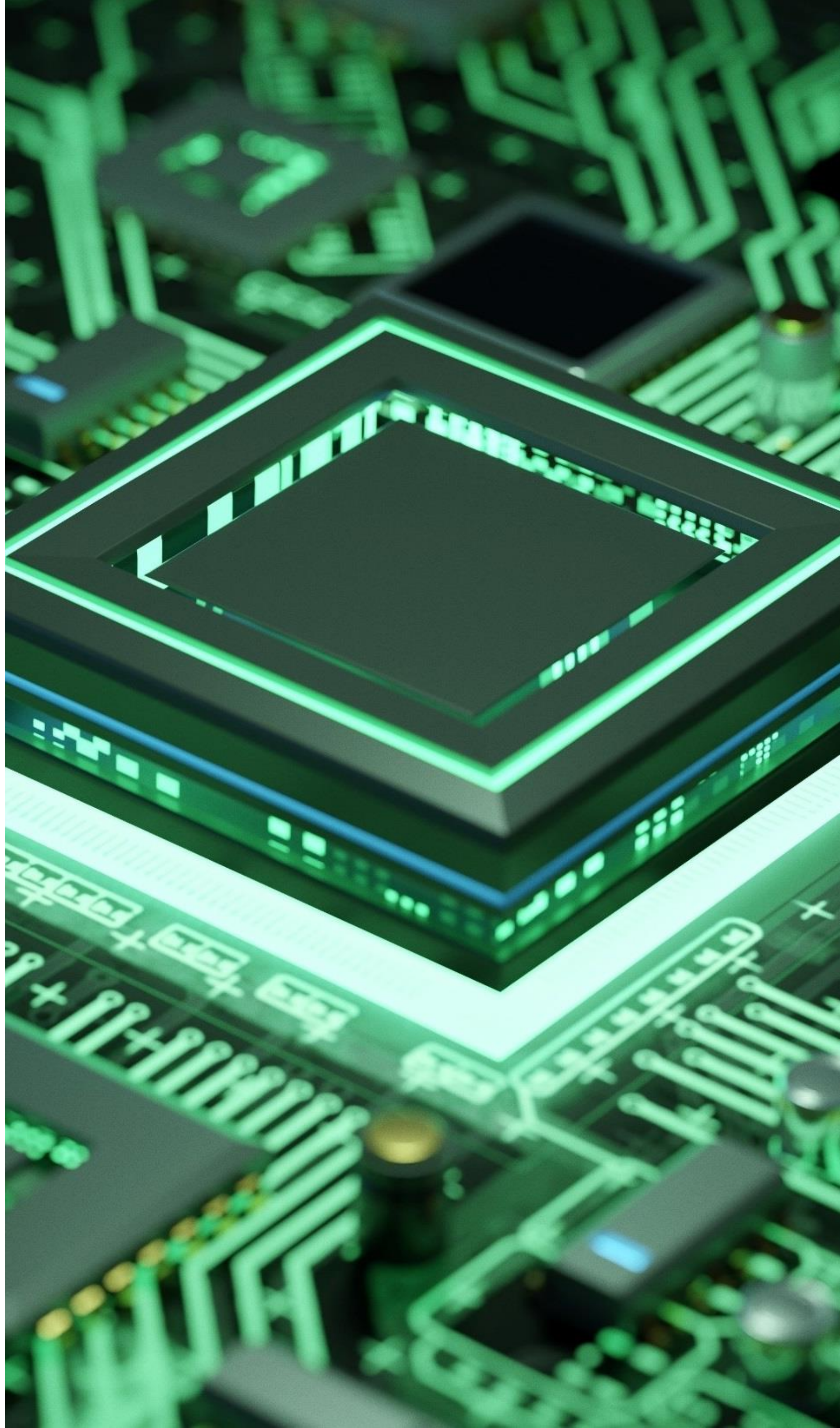
1 Adjusted for divested MicroOptics business

Key CEO messages

Q3 order intake was lower compared to previous quarters, as HBM customers are busy with the installation and ramp-up of high-volume production. Additionally, demand from China is normalizing noticeably in both divisions as expected.

With sales of € 102.5 million and an EBIT margin of 16.9%, Q3 was our best quarter this year so far. Our efforts to increase production capacity are paying off - we are delivering more tools to our customers than ever before.

We are working on further increasing our production capacity, not only due to the current high demand with an order book of € 430.8 million, but also in preparation for further targeted growth in the coming years.



Strong growth and improving profitability in the first three quarters of 2024

in € million	9M 2024	9M 2023	Change
Order intake	276.2	281.2	-1.8%
Order book as of September 30	430.8	414.7	+3.9%
Sales	295.3	202.3	+46.0%
Gross profit	116.8	67.7	+72.5%
Gross profit margin	39.6%	33.5%	+6.1pp
EBIT	47.4	12.8	+270.3%
EBIT margin	16.1%	6.3%	+9.8pp
Earnings after taxes (continuing operations)	35.4	9.8	+261.2%
Net profit[1]	93.8	5.0	
EPS basic (in €, continuing operations)	1.85	0.51	+262.7%
EPS basic (in €)[1]	4.90	0.26	-
Net cash	122.3	32.7	+274.0%
Free cash flow (continuing operations)	24.2	0.1	
Free cash flow total[1]	95.0	-5.6	
Employees as of September 30	1,414	1,133	+24.8%

[1] including discontinued operations, i.e. MicroOptics business

- Order intake in the first nine months slightly below previous year, mainly due to expected normalized demand from Chinese customers
- Gross profit margin increased significantly, benefiting from favorable product and customer mix and high capacity utilization; EBIT margin also benefited from disproportionate increase in OPEX
- Net profit of € 93.8 million includes result from discontinued operations (€ 58.3 million), i.e. the sale of our MicroOptics business
- Improved 9M.2024 free cash flow from continuing operations of € 24.2 million demonstrates ability to convert higher volume and margin improvements into cash

Division Overview 9M 2024

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Advanced Backend Solutions

in € million	9M.2024	9M.2023
Order intake	198.1	187.1
Order book	274.2	244.9
Sales	208.8	146.9
Gross profit	86.8	51.7
Gross profit margin	41.6%	35.2%
EBIT	33.3	10.2
EBIT margin	16.0%	6.9%

- Order intake up 5.9% year-on-year, despite a € 29 million decline in orders from Chinese customers; orders for coating systems improved in Q3
- Significant sales growth of € 61.9 million or 42.1% versus 9M 2023, mainly driven by execution of AI-connected bonder orders received in H2 2023; bonder sales thus almost tripled year-on-year
- Gross profit margin improved by 6.4pp to 41.6% thanks to high sales volume and favorable product and customer mix; all three quarters with gross profit margin >40%

Photomask Solutions

in € million	9M.2024	9M.2023
Order intake	78.1	94.1
Order book	156.7	169.9
Sales	86.5	55.5
Gross profit	30.6	16.2
Gross profit margin	35.5%	29.2%
EBIT	17.9	6.2
EBIT margin	20.7%	11.2%

- Expected normalization of Chinese customers' order behavior leads to € 16.0 million decline in order intake to € 78.1 million
- Strong order book level of ~ € 157 million provides high visibility and capacity utilization through mid-2025
- Ability to execute orders allows for significant sales growth of 55.9%
- Gross profit margin and EBIT margin benefited from strong product and customer mix as well as from very high sales level

Based on a strong Q3 performance well on track to achieve upper half of the raised forecast

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Guidance 2024

(as of July 18, 2024)

Sales

in € million

380–410

Actual 2023:
€ 304.3 million

Initial guidance:
Sales of € 340–370 million

Gross profit margin

in %

38–40

Actual 2023:
34.1%

Initial guidance:
Gross profit margin of 35–38%

EBIT margin

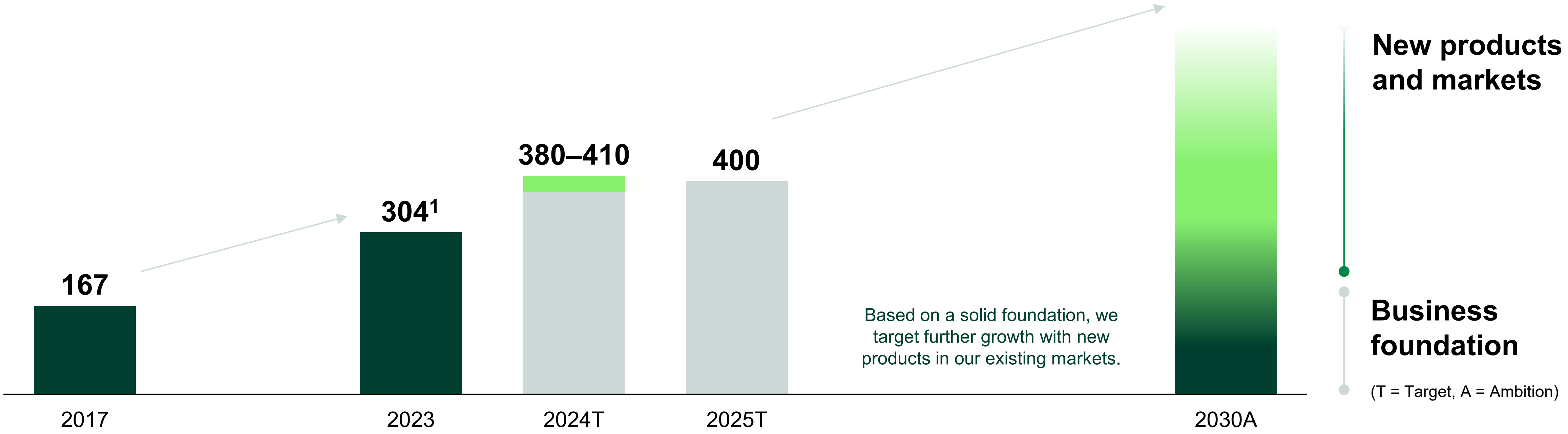
in %

14–16

Actual 2023:
9.1%

Initial guidance:
EBIT margin of 10–12%

Based on our business foundation we see further potential beyond



1 Major growth drivers 2023

Converting high order backlog in Photomask Solutions and Bonder business into sales growth

2 Major growth drivers 2024/2025

- Bonding (especially with regard to AI-driven demand for temporary bonders)
- Photomask Solutions

3 Major growth drivers 2030

- General expected market growth in our core businesses (lithography, bonding, photomask)
- Hybrid Bonding
- Wafer Cleaning

1 Excluding MicroOptics

Investor Relations information

Conference Calendar

November 21, 2024
Morgan Stanley Conference, Barcelona (IR-only)

November 25/26, 2024
German Equity Forum, Frankfurt (IR-only)

December 2, 2024
Berenberg European Conference, London

December 3, 2024
BofA Tech Virtual Field Trip, virtual

January 16, 2025
Needham Growth Conference, virtual (IR-only)

March 6, 2025
Berenberg EU Opportunities Conference, London

There may be changes to the SUSS conference schedule.

Financial Calendar

November 7, 2024
Q3 Report 2024

March 27, 2025
Annual Report 2024

May 8, 2025
Q1 Report 2025

June 3, 2025
Annual General Meeting

August 7, 2025
Half Year Report 2025

November 6, 2025
Q3 Report 2025

Disclaimer

This presentation contains forward-looking statements relating to the business. financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans. estimates. projections and expectations and are therefore subject to risks and uncertainties. most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently. actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.

Thank you

Growing Innovation

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